

SOT1627-1

HBGA620, plastic, thermal enhanced ball grid array; 620 balls;
1 mm pitch; 29 mm x 29 mm x 2.46 mm body

23 August 2018

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA620
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
JEDEC package outline code	MS-034 AAM-1
Mounting method type	S (surface mount)
Issue date	01-02-2016
Manufacturer package code	98ARE10568D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	29	-	mm
package width	-	29	-	mm
package height	-	2.46	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	620	-	



HBGA620, plastic, thermal enhanced ball grid array; 620 balls; 1 mm pitch; 29 mm x 29 mm x 2.46 mm body

2 Package outline

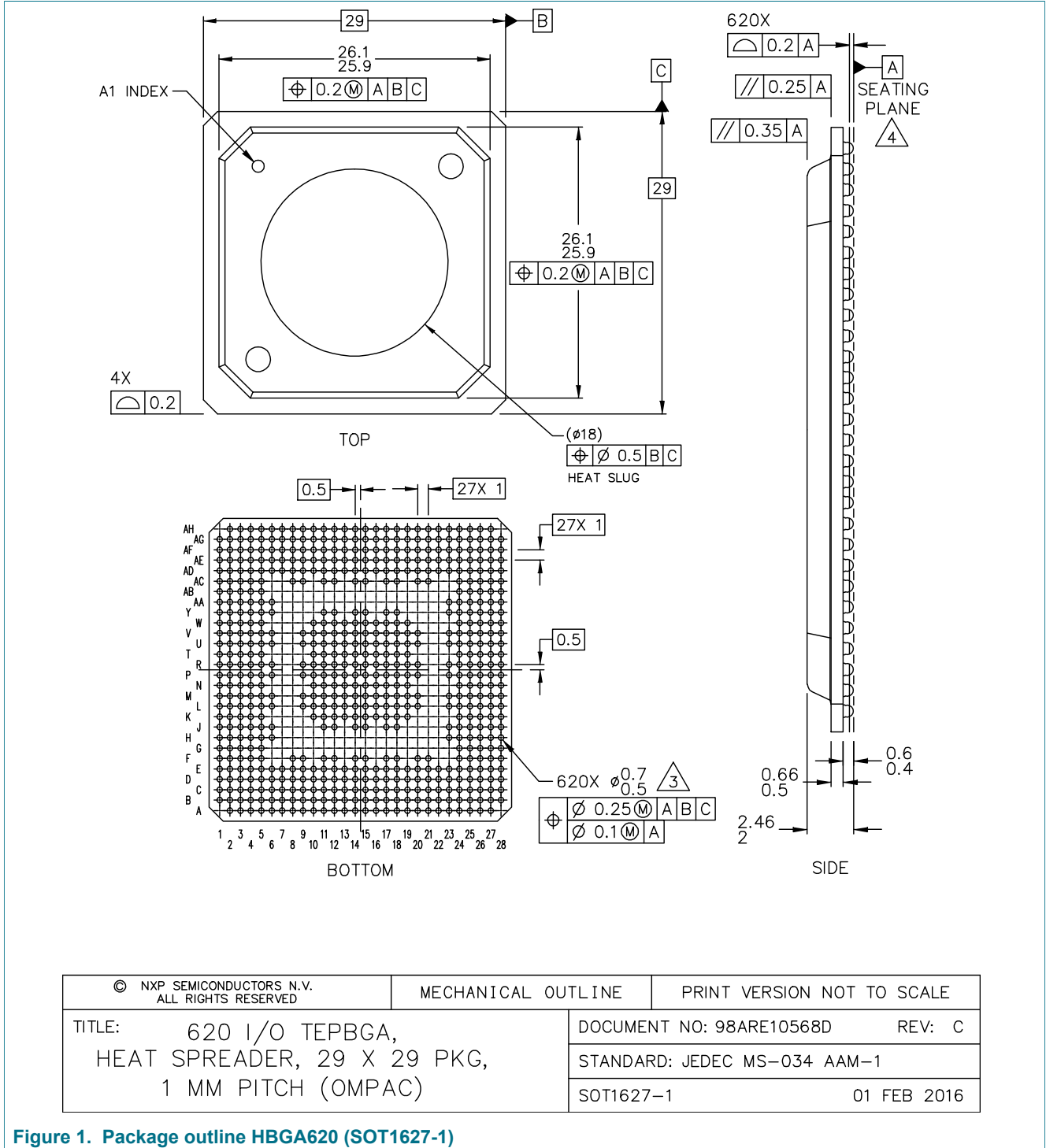


Figure 1. Package outline HBGA620 (SOT1627-1)

HBGA620, plastic, thermal enhanced ball grid array; 620 balls; 1 mm pitch; 29 mm x 29 mm x 2.46 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
5. PACKAGE CODE 5203 IS TO ACCOUNT FOR PGE AND THE BUILT-IN HEAT SPREADER.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: 620 I/O TEPBGA, HEAT SPREADER, 29 X 29 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARE10568D		REV: C
	STANDARD: JEDEC MS-034 AAM-1		
	SOT1627-1		01 FEB 2016

Figure 2. Package outline note HBGA620 (SOT1627-1)

3 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Contents

1	Package summary	1
2	Package outline	2
3	Legal information	4